

December 13, 2017

Subject: Notification of Business Division Transfer

Dear Valued Customer,

This letter is to notify you that Tecdia has completed an agreement to transition our Wafer Processing Equipment Business Division to Kumasan-Medix Co., Ltd. (see below) on December 13th, 2017. Products affected by this activity are Wafer Bonding, Grinding, Lapping, Scribing and Wafer Breaking machines. The transition encompasses all the functions under this business division ranging from design, manufacturing, sales and support. As we complete the transition of the business we will be continuing to accept purchase orders up until March 31st, 2017.

Kumasan-Medix Co., Ltd.

Mr. Tsuguhisa Shirase as CEO & President

Address: 2205 Shimosuzurikawamachi, Kita-ku, Kumamoto-shi, Kumamoto 861-5522, Japan

Phone: +81 096-355-3472

Website: <http://www.kumasan-medix.com/>

This notice is provided in compliance with requests for such notification and so that appropriate arrangements can be made at your company as necessary. Any questions should be directed to the undersigned or any local Tecdia office or representative.

Thank you for your patronage.

Sincerely,



Shinn Wolfe

Vice President, Tecdia Inc.

408-748-0100

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